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File: DWPI

Jan 31, 1987

DERWENT-ACC-NO: 1987-069182

DERWENT-WEEK: 198710

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TITLE: Electroconductive compsn. with improved tensile strength - comprises copper powder, glass frit opt. contg. lead oxide and vanadium pent:oxide

PRIORITY-DATA: 1985JP-0161455 (July 22, 1985)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> JP 62022868 A	January 31, 1987		004	

INT-CL (IPC): C09D 5/24; H01B 1/20

ABSTRACTED-PUB-NO: JP 62022868A

BASIC-ABSTRACT:

Compsn. comprises Cu powder, glass frit, and V2O5. Pref. compsn. comprises Cu powder 90-97.5 wt.%, glass frit 1.5-2.0 wt.%, V2O5 1-6 wt.% (excluding organic vehicle). Pref. frit contains PbO in amt. of above 50 wt. pts. per 100 pts. frit. Softening point of glass frit is lower by 250-400 deg.C than the burning temp. of electro-conductive paste. Pref. burning temp. of electro-conductive paste is 830-950 deg.C. Particle size of Cu is pref. 0.3-1.5 micron. Frit is pref. e.g. PbO-SiO2-B2O3-based glass, etc. PbO is pref. above 50 wt.%. Pref. electro-conductive paste is screen-printed and dried and then fired at 830-950 deg.C peak temp.

USE/ADVANTAGE - Compsn. is used for thick-film Cu paste. Prod. has good solder-wettability and tensile strength (adhesion).

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File: JPAB

Jan 31, 1987

PUB-NO: JP362022868A

DOCUMENT-IDENTIFIER: JP 62022868 A

TITLE: ELECTRICALLY CONDUCTIVE COMPOSITION

PUBN-DATE: January 31, 1987

INVENTOR-INFORMATION:

NAME

COUNTRY

YOSHIHARA, TOSHIO

ISHII, SHINJI

US-CL-CURRENT: 252/512

INT-CL (IPC): C09D 5/24; H01B 1/20

ABSTRACT:

PURPOSE: To provide an electrically conductive compsn. which has excellent solderability and tensile strength and gives thick-coating Cu paste which does not cause deterioration in characteristics by heat during soldering, containing Cu powder, glass frit and V2O5.

CONSTITUTION: 90~97.5wt% Cu powder having a particle size of 0.3~1.5 μ m, 1.5~2.0wt% glass frit (e.g. lead borosilicate glass) having a softening point of 250~400°C, which contains at least 50wt% PbO blended therewith, 1~6wt% V2O5 having a particle size of 2 μ m or below and optionally, dispersant and anti-foaming agent are mixed together to obtain an electrically conductive compsn. 12~16pts.wt. org. vehicle is mixed with 100pts.wt. compsn. The resulting electrically conductive paste is applied to a substrate by screen printing, dried and fired at a peak temp. of 830~950°C.

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